Lighting Color

Yellow GreenOrange

LN170WP38

Round Type

φ4.4 mm

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Yellow Green

Parameter	Symbol	Rating	Unit
Power dissipation	P _D	90	mW
Forward current	$I_{\rm F}$	30	mA
Pulse forward current *	I _{FP}	150	mA
Reverse voltage	V _R	4	V
Operating ambient temperature	T _{opr}	-25 to +85	°C
Storage temperature	T _{stg}	-30 to +100	°C

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

• Orange

Parameter	Symbol	Rating	Unit	
Power dissipation	PD	90	mW	
Forward current	I _F	30	mA	
Pulse forward current *	I _{FP}	150	mA	
Reverse voltage	V _R	3	V	
Operating ambient temperature	T _{opr}	-25 to +85	°C	
Storage temperature	T _{stg}	-30 to $+100$	°C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

Electro-Optical Characteristics $T_a = 25^{\circ}C$

• Yellow Green

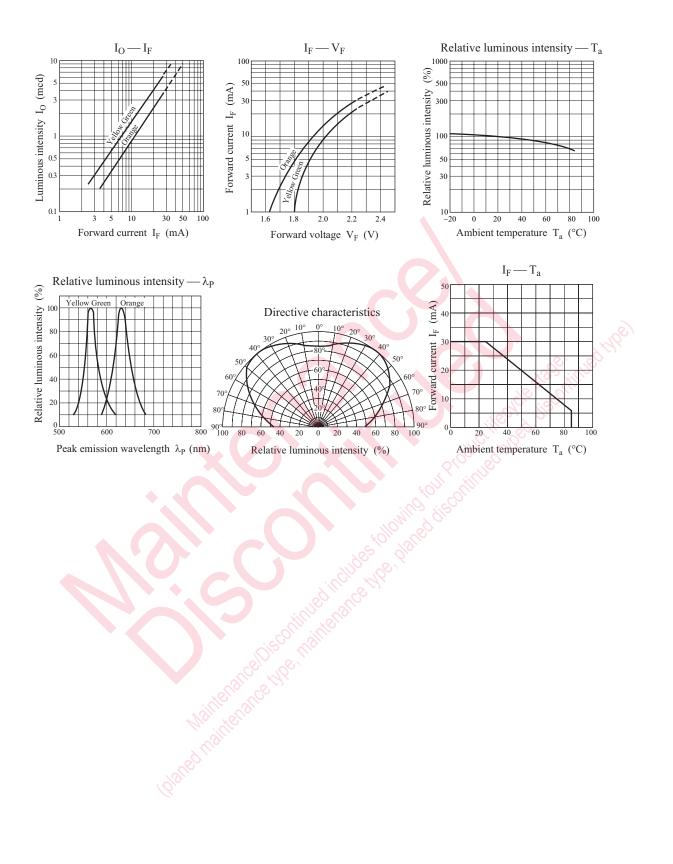
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O		0.8	4.0		mcd
Reverse current	IR	$V_R = 4 V$			10	μΑ
Forward voltage	VF	$I_{\rm F} = 20 {\rm mA}$		2.2	2.50	V
Peak emission wavelength	λ _P	$I_{\rm F} = 20 {\rm mA}$		565		nm
Spectral half band width	Δλ	$I_{\rm F} = 20 {\rm mA}$		30		nm

• Orange

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	Io		0.5	2.5		mcd
Reverse current	I _R	$V_R = 3 V$			10	μΑ
Forward voltage	V _F	$I_{\rm F} = 20 {\rm mA}$		2.1	2.45	V
Peak emission wavelength	λ_{P}	$I_{\rm F} = 20 \ {\rm mA}$		630		nm
Spectral half band width	Δλ	$I_{\rm F} = 20 \text{ mA}$		40		nm

LN170WP38

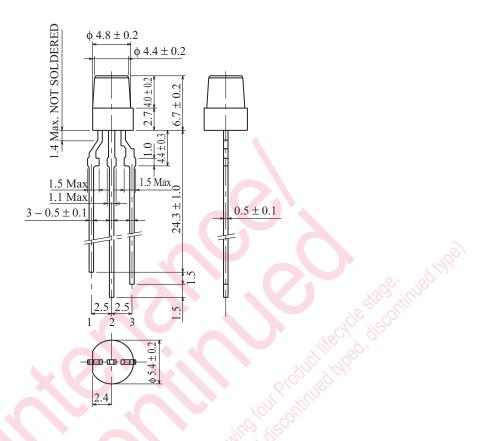
Panasonic



Panasonic

Package (Unit: mm)

LLXFTN3SH702



• Pin name

- 1: Anode (Orange)
- 2: Cathode (Common)
- 3: Anode (Yellow Green)

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